

#### **Features**

- ESD Protect for 2 Lines with Bi-directional
- Provide ESD protection for the protected line to IEC 61000-4-2 (ESD) ±15kV (air), ±15kV (contact)
  IEC 61000-4-4 (EFT) 50A (5/50ns)
  Cable Discharge Event (CDE)
- Ultra-small DFN1006P3X package (1.0mmx0.6mmx0.45mm) saves board space
- Protect two I/O lines or two power lines
- Fast turn-on and Low clamping voltage
- Low operating voltage: 5V maximum
- Solid-state silicon-avalanche and active circuit triggering technology
- Green Part

#### **Applications**

- Mobile Phones
- Hand Held Portable Applications
- Computer Interfaces Protection
- Microprocessors Protection
- Serial and Parallel Ports Protection
- Control Signal Lines Protection
- Power lines on PCB Protection
- Latchup Protection

# **Description**

AZ5125-02F is a design which includes two bi-directional ESD rated clamping cells to protect two power lines, or two control lines, or two low speed data lines in an electronic systems. The AZ5125-02F has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), and Cable Discharge Event (CDE).

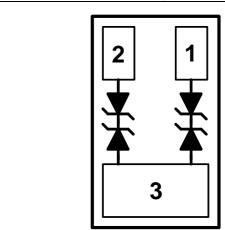
AZ5125-02F is a unique design which includes

proprietary clamping cells in a single package. During transient conditions, the proprietary clamping cells prevent over-voltage on the power lines or control/data lines, protecting any downstream components.

AZ5125-02F is bi-directional and may be used on lines where the signal swings above and below ground.

AZ5125-02F may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

# Circuit Diagram / Pin Configuration



DFN1006P3X (Bottom View) (1.0mm x 0.6mm x 0.45mm)

## **SPECIFICATIONS**

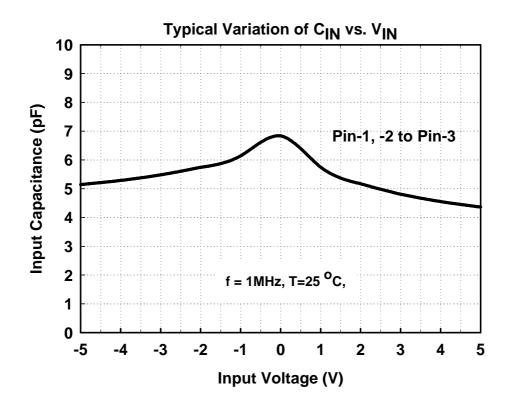
ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	RATING	UNITS	
Operating Supply Voltage (pin-1,-2 to pin-3)	V <sub>DC</sub>	±5.5	V	
ESD per IEC 61000-4-2 (Air)	\/	±15	14/	
ESD per IEC 61000-4-2 (Contact)	V <sub>ESD</sub>	±15	kV	
Lead Soldering Temperature	T <sub>SOL</sub>	260 (10 sec.)	°C	
Operating Temperature	T <sub>OP</sub>	-55 to +85	℃	
Storage Temperature	T <sub>STO</sub>	-55 to +150	$^{\circ}$	

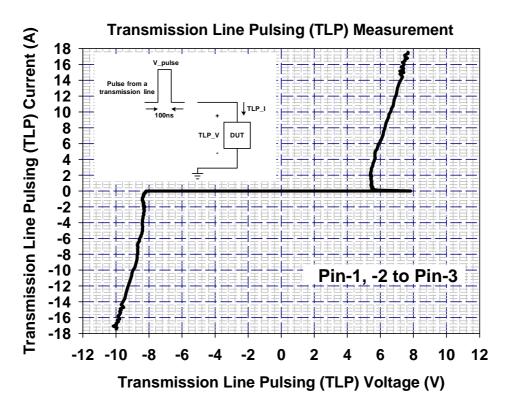
ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MINI	TYP	MAX	UNITS
Reverse Stand-Off	\/	T=25 °C	ç,		5	V
Voltage	$V_{RWM}$	1=25 C				
Reverse Leakage	1	V <sub>RMM</sub> = ±5V, T=25 °C.			1	^
Current	l <sub>Leak</sub>	V <sub>RWM</sub> = ±3V, 1=23 C.			ı	μА
Reverse	\/	I <sub>BV</sub> = 1mA, T=25 °C.	5.7		9	V
Breakdown Voltage	$V_{BV}$	I <sub>BV</sub> = IIIIA, 1=23 C.	5.7		9	V
ESD Clamping	\ /	IEC 61000-4-2 +6kV, T=25 °C,		11		V
Voltage	$V_{ESD\_CL}$	Contact mode				V
Channel Input		$V_R$ = 0V, f = 1MHz, T=25 °C.		7	8.5	pΕ
Capacitance	C <sub>IN</sub>			/	0.0	pF

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#### **Typical Characteristics**







#### **Applications Information**

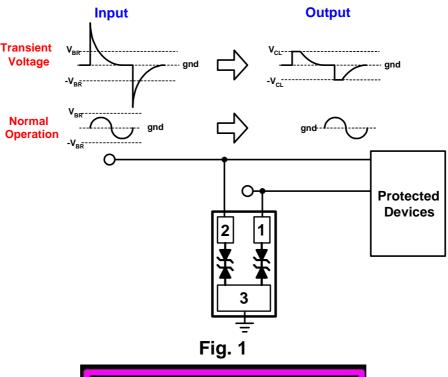
The AZ5125-02F is designed to protect two lines against System ESD/EFT/Cable-Discharging pulses by clamping them to an acceptable reference. It provides bi-directional protection.

The usage of the AZ5125-02F is shown in Fig. 1. Protected lines, such as data lines, control lines, or power lines, are connected at pin 1 and pin 2 respectively. The pin 3 is connected to a ground plane on the board. In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ5125-02F should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ5125-02F.
- Place the AZ5125-02F near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

Fig. 2 shows an example of PCB layout for speaker.



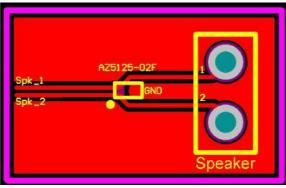
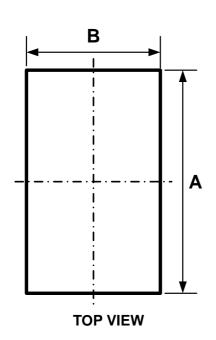


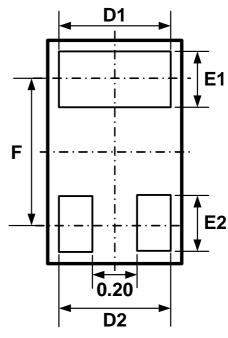
Fig. 2



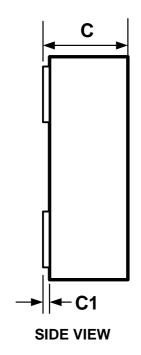
## **Mechanical Details**

**DFN1006P3X**PACKAGE DIAGRAMS AND DIMENSIONS





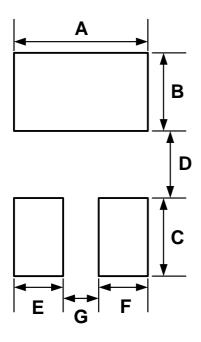
**BOTTOM VIEW (unit in mm)** 



SYMBOL	Millimeters			
STIVIBUL	MIN.	NOM.	MAX.	
Α	0.95	1.00	1.05	
В	0.55	0.60	0.65	
С	0.41	0.45	0.50	
C1	0.00	0.02	0.05	
D1	0.45	0.50	0.55	
D2	0.45	0.50	0.55	
E1	0.20	0.25	0.30	
E2	0.20	0.25	0.30	
F		0.65		



#### LAND LAYOUT

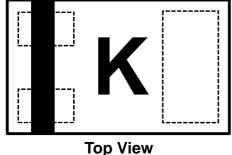


Dimensions				
Index	Millimeter	Inches		
Α	0.600	0.024		
В	0.350	0.014		
С	0.350	0.014		
D	0.300	0.012		
E	0.225	0.009		
F	0.225	0.009		
G	0.150	0.006		

#### Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

#### **MARKING CODE**



Top	View
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Part Number	Marking Code
AZ5125-02F (Green part)	К

Note. Green means Pb-free, RoHS, and Halogen free compliant.



**Ordering Information** 

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ5125-02F.R7GR	Green	T/R	7 inch	12,000/reel	4 reel=48,000/box	6 box=288,000/carton

# **Revision History**

Revision	Modification Description
Revision 2012/07/18	Preliminary Release.
Revision 2012/08/31	Formal Release.
Revision 2012/09/19	Add an example of PCB layout.
Revision 2015/04/15	Add the Ordering Information.